Zenglin Wang

List of Publications by Year
in descending order

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76	1,964	201658 27	289230 40
papers	citations	h-index	g-index

76	76	76	1999
all docs	docs citations	times ranked	citing authors

#	Article	IF	Citations
1	Synergistic Nanotubular Copperâ€Doped Nickel Catalysts for Hydrogen Evolution Reactions. Small, 2018, 14, e1704137.	10.0	111
2	Hierarchical nanoporous Ni(Cu) alloy anchored on amorphous NiFeP as efficient bifunctional electrocatalysts for hydrogen evolution and hydrazine oxidation. Journal of Catalysis, 2019, 373, 180-189.	6.2	85
3	Preparation of Ag-Nanoparticle-Loaded MnO₂ Nanosheets and Their Capacitance Behavior. Energy & Fuels, 2012, 26, 618-623.	5.1	82
4	Fabrication of Nanoporous Nickelâ€"Iron Hydroxylphosphate Composite as Bifunctional and Reversible Catalyst for Highly Efficient Intermittent Water Splitting. ACS Applied Materials & Interfaces, 2017, 9, 35837-35846.	8.0	76
5	Effects of Li content on the phase structure and electrical properties of lead-free (K0.46â^’xâ^•2Na0.54â^’xâ^•2Lix)(Nb0.76Ta0.20Sb0.04)O3 ceramics. Applied Physics Letters, 2007, 90, 232905.	3.3	73
6	Phase transitional behavior, microstructure, and electrical properties in Ta-modified [(K0.458Na0.542)0.96Li0.04]â€ˆNbO3 lead-free piezoelectric ceramics. Journal of Applied Physics, 2008, 104, .	2.5	72
7	Bottom-Up Fill for Submicrometer Copper Via Holes of ULSIs by Electroless Plating. Journal of the Electrochemical Society, 2004, 151, C781.	2.9	70
8	Bifunctional Copper-Doped Nickel Catalysts Enable Energy-Efficient Hydrogen Production via Hydrazine Oxidation and Hydrogen Evolution Reduction. ACS Sustainable Chemistry and Engineering, 2018, 6, 12746-12754.	6.7	68
9	Adhesion improvement of electroless copper to a polyimide film substrate by combining surface microroughening and imide ring cleavage. Journal of Adhesion Science and Technology, 2002, 16, 1027-1040.	2.6	55
10	2-Mercaptopyridine as a new leveler for bottom-up filling of micro-vias in copper electroplating. Electrochimica Acta, 2016, 208, 33-38.	5.2	53
11	Suppression of native oxide growth in sputtered TaN films and its application to Cu electroless plating. Journal of Applied Physics, 2003, 94, 4697-4701.	2.5	48
12	Fabrication of 3D microporous amorphous metallic phosphides for high-efficiency hydrogen evolution reaction. Electrochimica Acta, 2019, 306, 651-659.	5.2	48
13	Fabrication of TiO₂(B)/Anatase Heterophase Junctions at High Temperature via Stabilizing the Surface of TiO₂(B) for Enhanced Photocatalytic Activity. Journal of Physical Chemistry C, 2019, 123, 1779-1789.	3.1	43
14	Phase coexistence and high electrical properties in (KxNa0.96â^’xLi0.04)(Nb0.85Ta0.15)O3 piezoelectric ceramics. Journal of Applied Physics, 2009, 105, 054101.	2.5	41
15	Investigation of Nitrogen Heterocyclic Compounds as Levelers for Electroplating Cu Filling by Electrochemical Method and Quantum Chemical Calculation. Journal of the Electrochemical Society, 2015, 162, D509-D514.	2.9	37
16	Study of an Environmentally Friendly Surface Etching System of ABS for Improving Adhesion of Electroless Cu film. Journal of the Electrochemical Society, 2011, 158, D664.	2.9	36
17	Study of an environment-friendly surface pretreatment of ABS-polycarbonate surface for adhesion improvement. International Journal of Adhesion and Adhesives, 2013, 44, 243-249.	2.9	36
18	Tetrazole Derived Levelers for Filling Electroplated Cu Microvias: Electrochemical Behaviors and Quantum Calculations. Electrochimica Acta, 2015, 178, 546-554.	5.2	36

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19	Pulsed electrodeposition of well-ordered nanoporous Cu-doped Ni arrays promotes high-efficiency overall hydrazine splitting. Journal of Materials Chemistry A, 2020, 8, 21084-21093.	10.3	36
20	A study of bottom-up electroplated copper filling by the potential difference between two rotating speeds of a working electrode. Journal of Electroanalytical Chemistry, 2014, 712, 25-32.	3.8	35
21	Controllable electrochemical synthesis of Ag nanoparticles in ionic liquid microemulsions. Electrochemistry Communications, 2015, 58, 41-45.	4.7	34
22	Phase Structure, Microstructure, and Electrical Properties of Sbâ€Modified (K, Na, Li) (Nb, Ta) O₃ Piezoelectric Ceramics. Journal of the American Ceramic Society, 2008, 91, 2211-2216.	3.8	33
23	An Environment-Friendly Surface Pretreatment of ABS Resin Prior to Electroless Plating. Electrochemical and Solid-State Letters, 2009, 12, D92.	2.2	33
24	Electrodeposition of porous MoO42--doped NiFe nanosheets for highly efficient electrocatalytic oxygen evolution reactions. Electrochimica Acta, 2018, 260, 477-482.	5.2	33
25	Fabrication of TiO 2 (B)/anatase heterophase junctions in nanowires via a surface-preferred phase transformation process for enhanced photocatalytic activity. Chinese Journal of Catalysis, 2018, 39, 1500-1510.	14.0	33
26	Ultralow Fe^{III} Ion Doping Triggered Generation of Ni₃S₂ Ultrathin Nanosheet for Enhanced Oxygen Evolution Reaction. ChemCatChem, 2019, 11, 2011-2016.	3.7	29
27	Bottom-up copper fill with addition of mercapto alkyl carboxylic acid in electroless plating. Electrochimica Acta, 2006, 51, 2442-2446.	5.2	28
28	Electrodeposition of Cobalt Nickel Hydroxide Composite as a High-Efficiency Catalyst for Hydrogen Evolution Reactions. Journal of the Electrochemical Society, 2017, 164, H587-H592.	2.9	27
29	Ni-based 3D hierarchical heterostructures achieved by selective electrodeposition as a bifunctional electrocatalyst for overall water splitting. Electrochimica Acta, 2021, 379, 138042.	5.2	26
30	Hepatitis B virus evades immune recognition via RNA adenosine deaminase ADAR1-mediated viral RNA editing in hepatocytes. Cellular and Molecular Immunology, 2021, 18, 1871-1882.	10.5	26
31	Characterization of sputtered tungsten nitride film and its application to Cu electroless plating. Microelectronic Engineering, 2008, 85, 395-400.	2.4	25
32	Simultaneous determination of multiple phytohormones in tomato by ionic liquid-functionalized carbon fibers-based solid-phase microextraction coupled with liquid chromatography-mass spectrometry. Analytica Chimica Acta, 2020, 1137, 143-155.	5.4	23
33	Adhesion Improvement of ABS Resin to Electroless Copper by H2SO4â€“MnO2 Colloid with Ultrasound-Assisted Treatment. Journal of Adhesion Science and Technology, 2011, 25, 1211-1221.	2.6	22
34	Bottom-up fill mechanisms of electroless copper plating with addition of mercapto alkyl carboxylic acid. Journal of Vacuum Science & Technology B, 2006, 24, 803.	1.3	21
35	Improvement in the Etching Performance of the Acrylonitrileâ€“Butadieneâ€“Styrene Resin by MnO₂â€“H₃PO₄â€“H₂SO₄ Colloid. Langmuir, 2013, 29, 5968-5973.	3.5	20
36	Bottom-Up Filling in Electroless Plating with an Addition of PEGâ€“PPG Triblock Copolymers. Electrochemical and Solid-State Letters, 2010, 13, D47.	2.2	19

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37	Surface modification of ABS by photocatalytic treatment for electroless copper plating. Journal of Adhesion Science and Technology, 2014, 28, 499-511.	2.6	19
38	Effect of the molecular chains grafted on graphene nanosheets on the properties of poly(<scp>l</scp>â€lactic acid) nanocomposites. Polymer Composites, 2017, 38, 5-12.	4.6	19
39	Monodispersed silver-palladium nanoparticles for ethanol oxidation reaction achieved by controllable electrochemical synthesis from ionic liquid microemulsions. Journal of Colloid and Interface Science, 2019, 557, 450-457.	9.4	18
40	Surface Assistant Charge Separation in PEC Cu₂Sâ€“Ni/Cu₂O Cathode. ACS Applied Materials & Interfaces, 2019, 11, 34000-34009.	8.0	18
41	Electrochemical modification and tuning Ni/Ni(OH)2â€“Ag heterogeneous interface for efficient electrocatalytic hydrogen and oxygen evolution reactions. Electrochimica Acta, 2020, 341, 136051.	5.2	18
42	Highly isolated Pt NPs embedded in porous TiO2 derived from MIL-125 with enhanced photocatalytic hydrogen production activity. Journal of Catalysis, 2021, 402, 289-299.	6.2	17
43	Syntheses, characterization and crystal structures of 5,14-dihydro-6,8,15,17-tetramethyldibenzo[b,i][1,4,8,11]tetraazacyclotetradecine rare earth(III) complexes. Journal of the Chemical Society Dalton Transactions, 1999, , 1695-1700.	1.1	15
44	Influence of Surface Oxide of Sputtered TaN on Displacement Plating of Cu. Japanese Journal of Applied Physics, 2003, 42, 1843-1846.	1.5	15
45	Effect of Additives on Hole Filling Characteristics of Electroless Copper Plating. Japanese Journal of Applied Physics, 2004, 43, 7000-7001.	1.5	15
46	Design and achievement of a complete bottom-up electroless copper filling for sub-micrometer trenches. Electrochimica Acta, 2011, 56, 3317-3321.	5.2	15
47	Effect of initial temperature on joint of aluminum alloy to galvanized steel welded by MIG arc brazing-fusion welding process. International Journal of Advanced Manufacturing Technology, 2016, 86, 3135-3143.	3.0	15
48	A Synergy Effect of 2-MBT and PE-3650 on the Bottom-Up Filling in Electroless Copper Plating. Electrochemical and Solid-State Letters, 2011, 14, D107.	2.2	14
49	Robust Conductive Micropatterns on PTFE Achieved via Selective UV-Induced Graft Copolymerization for Flexible Electronic Applications. ACS Applied Materials & Interfaces, 2019, 11, 5517-5525.	8.0	14
50	Synthesis, characterization and crystal structure of a 6,8,15,17-tetramethyldibenzo [b,i] (1,4,8,11)tetraaza (14)-annulene yttrium (III) complex. Polyhedron, 1998, 17, 4451-4456.	2.2	13
51	Highly Adhesive Electroless Cu Layer Formation Using an Ultra Thin Ionized Cluster Beam (ICB)-Pd Catalytic Layer for Sub-100 nm Cu Interconnections. Japanese Journal of Applied Physics, 2003, 42, L1223-L1225.	1.5	13
52	Improved electrochemical performance of nickel-cobalt hydroxides by electrodeposition of interlayered reduced graphene oxide. International Journal of Hydrogen Energy, 2019, 44, 3658-3667.	7.1	13
53	HF promoted increased nitrogen doping in TiO₂(B) photocatalyst. Chemical Communications, 2020, 56, 5609-5612.	4.1	13
54	Adhesion improvement of electroless copper to PC substrate by a low environmental pollution MnO2â€“H3PO4â€“H2SO4â€“H2O system. International Journal of Adhesion and Adhesives, 2013, 41, 50-56.	2.9	12

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55	Electrochemical Research of a Stable Electroless Silver Bath. Journal of the Electrochemical Society, 2016, 163, D121-D125.	2.9	12
56	Copper (0) Doping Makes Cobalt-Nickel Hydroxide a High-Efficiency Catalyst for Hydrogen Evolution Reaction. Journal of the Electrochemical Society, 2018, 165, H866-H871.	2.9	12
57	First Synergy Effects of SPS and PEG-4000 on the Bottom-Up Filling in Electroless Copper Plating. Journal of the Electrochemical Society, 2010, 157, D546.	2.9	10
58	The effect of TiO₂morphology on the surface modification of poly (ethylene) Tj ETQq0 0 0 rgBT /Overlock 10 Tf 50 622 Td (	2.6	9
59	Vibration and Buckling Analysis of Piezoelectric Nanowires Based on Surface Energy Density. Acta Mechanica Solida Sinica, 2021, 34, 425-436.	1.9	9
60	Characterization of Electroless-Plated Cu Film over Pd Catalytic Layer Formed by an Ionized Cluster Beam. Journal of the Electrochemical Society, 2005, 152, C684.	2.9	8
61	Effects of Triethanolamine and K[sub 4][Fe(CN)[sub 6]] upon Electroless Copper Plating. Journal of the Electrochemical Society, 2010, 157, D500.	2.9	7
62	Surface modification of polyimide by combining swelling and TiO₂ photocatalytic treatments for adhesion improvement of electroless Cu. Journal of Adhesion Science and Technology, 2019, 33, 371-381.	2.6	7
63	Electrochemical Synthesis of Continuous Controllable Ag Nanoparticles from Quaternary Ionic Liquid Microemulsions and Electrocatalytic Activity. Journal of the Electrochemical Society, 2016, 163, D442-D446.	2.9	6
64	Electrodeposited of ultrathin VOx-doped NiFe layer on porous NiCo phosphide for efficient overall water splitting. Applied Physics Letters, 2021, 119, .	3.3	6
65	Comparison of Bottom-up Filling in Electroless Plating with an Addition of PEG, PPG and EPE. Chinese Journal of Chemistry, 2011, 29, 422-426.	4.9	5
66	A study of the environmentally friendly polycarbonate surface etching system containing H₂SO₄â€“MnO₂colloid. Journal of Adhesion Science and Technology, 2013, 27, 1455-1463.	2.6	5
67	A New Surface Etching Method Using MnO ₂ /H ₂ SO ₄ Colloid for Adhesion Improvement of Epoxy Polymer. Journal of Adhesion Science and Technology, 2012, 26, 1407-1417.	2.6	4
68	Photocatalytic Surface Modification of PI Film for Electroless Copper Plating. Advances in Condensed Matter Physics, 2018, 2018, 1-8.	1.1	3
69	Boussinesq problem with the surface effect based on surface energy density. International Journal of Mechanics and Materials in Design, 2020, 16, 633-645.	3.0	3
70	Adhesion improvement of ABS resin by MnO2-H3PO4-H2SO4 colloid with ultrasound-assisted etching treatment. Journal of Adhesion Science and Technology, 0, , 1-11.	2.6	3
71	Analysis of multiple-phytohormones during fruit development in strawberry by using miniaturized dispersive solid-phase extraction based on ionic liquid-functionalized carbon fibers. Journal of Food Composition and Analysis, 2022, 106, 104262.	3.9	3
72	Effect of additive triblock copolymer PEP-3100 on bottom-up filling in electroless copper plating. Russian Journal of Electrochemistry, 2012, 48, 99-103.	0.9	2

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73	Soft Templateâ€Directed Reactions: Oneâ€Pot Synthetic Route for Bimetallic Coreâ€"Satelliteâ€"Shell Structured Electrocatalytic Nanospheres. ChemCatChem, 2018, 10, 2546-2550.	3.7	1
74	Cu Filling Characteristics in Through-Si Via Holes by Electroless Plating with Addition of Inhibitors. ECS Transactions, 2009, 16, 27-32.	0.5	0
75	Influence of Surface Oxide of Sputtered TaN Film on Displacement Plating of Cu. , 2002, , .		0
76	Electroless Copper Seed Activated by 1nm ICB-Pd Catalytic Layer for Fine Cu Interconnections. , 2003, , .		0